

November 2013

# **FQI4N90**

# N-Channel QFET® MOSFET

900 V, 4.2 A, 3.3 Ω

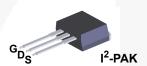
# **Description**

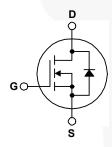
This N-Channel enhancement mode power MOSFET is • 4.2 A, 900 V,  $R_{DS(on)}$  = 3.3  $\Omega$  (Max.) @  $V_{GS}$  = 10 V, produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state

• Low Gate Charge (Typ. 24 nC) resistance, and to provide superior switching performance • Low Crss (Typ. 9.5 pF) and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power • 100% Avalanche Tested factor correction (PFC), and electronic lamp ballasts.

# **Features**

- $I_D = 2.1 A$





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQI4N90TU	Unit
V <sub>DSS</sub>	Drain-Source Voltage		900	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		4.2	Α
	- Continuous (T <sub>C</sub> = 100°C)		2.65	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	16.8	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	570	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	4.2	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	14	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.0	V
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		3.13	W
	Power Dissipation (T <sub>C</sub> = 25°C)		140	W
	- Derate above 25°C		1.12	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C

# **Thermal Characteristics**

Symbol	Parameter	FQI4N90TU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.89	
D	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	62.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in <sup>2</sup> Pad of 2-oz Copper), Max.	40	

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQI4N90TU	FQI4N90	I <sup>2</sup> -PAK	Tube	N/A	N/A	50 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.9		V/°C
I <sub>DSS</sub>	Zana Cata Valta na Duain Cumant	V <sub>DS</sub> = 900 V, V <sub>GS</sub> = 0 V			10	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 720 V, T <sub>C</sub> = 125°C			100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.1 A		2.7	3.3	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 2.1 A		3.5		S
	ic Characteristics					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		860	1100	pF
C <sub>oss</sub>	Output Capacitance			90	120	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			9.5	12.5	pF
Switch	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 450 V, I <sub>D</sub> = 4.2 A,		25	60	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 450 \text{ V}, I_{D} = 4.2 \text{ A},$ $R_{G} = 25 \Omega$		70	150	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	11.6 20 32		45	100	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		40	90	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 720 V, I <sub>D</sub> = 4.2 A,		24	30	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		5.8		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)	/	11.5		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				4.2	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				16.8	Α
	5 . 6 . 5 5	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 4.2 A			1.4	V
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	VGS - 0 V, IS - 4.2 A			1.4	V
V <sub>SD</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 4.2 \text{ A},$		440		ns

**Notes:** 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 61 mH, I $_{AS}$  = 4.2 A, V $_{DD}$  = 50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C. 3. I $_{SD}$  ≤ 4.2 A, di/dt ≤ 200 A/ $\mu$ s, V $_{DD}$  ≤ BV $_{DSS}$ , starting T $_{J}$  = 25°C. 4. Essentially independent of operating temperature.

# **Typical Characteristics**

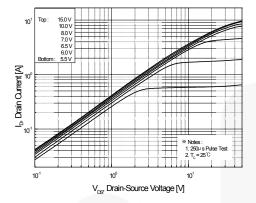


Figure 1. On-Region Characteristics

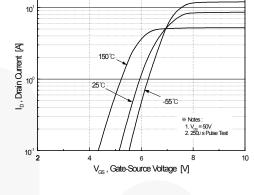


Figure 2. Transfer Characteristics

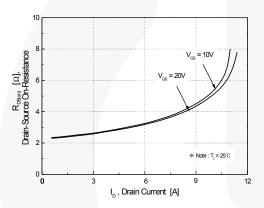


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

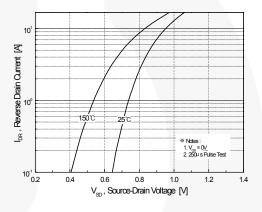


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

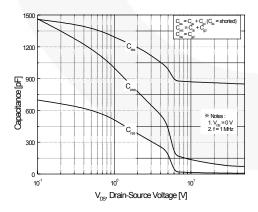


Figure 5. Capacitance Characteristics

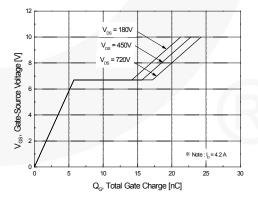


Figure 6. Gate Charge Characteristics

# 12 (Daily Montalized) 10 (Source Bread and Source Bread a

0.8 L -100

Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

T, Junction Temperature [°C]

150

200

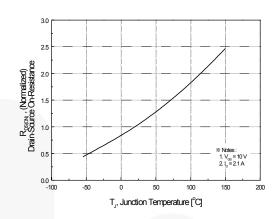


Figure 8. On-Resistance Variation vs. Temperature

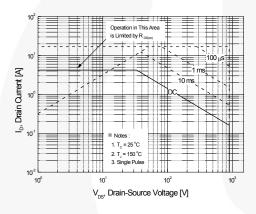


Figure 9. Maximum Safe Operating Area

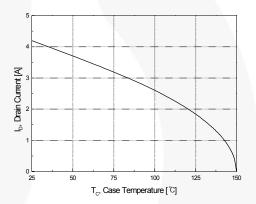


Figure 10. Maximum Drain Current vs. Case Temperature

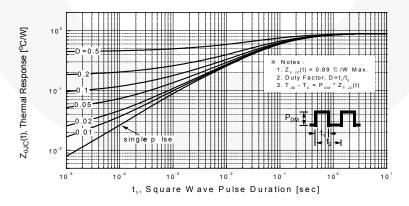


Figure 11. Transient Thermal Response Curve

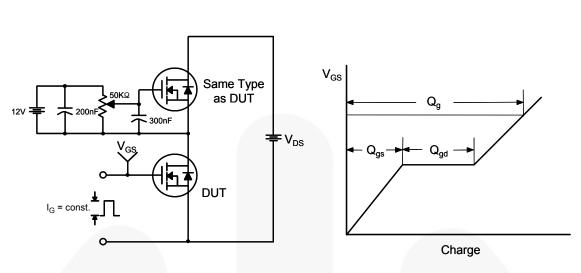


Figure 12. Gate Charge Test Circuit & Waveform

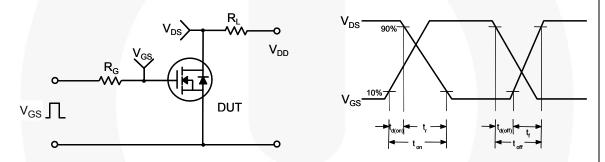


Figure 13. Resistive Switching Test Circuit & Waveforms

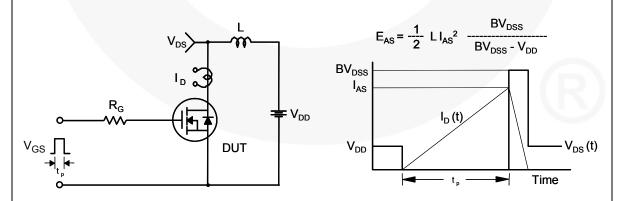
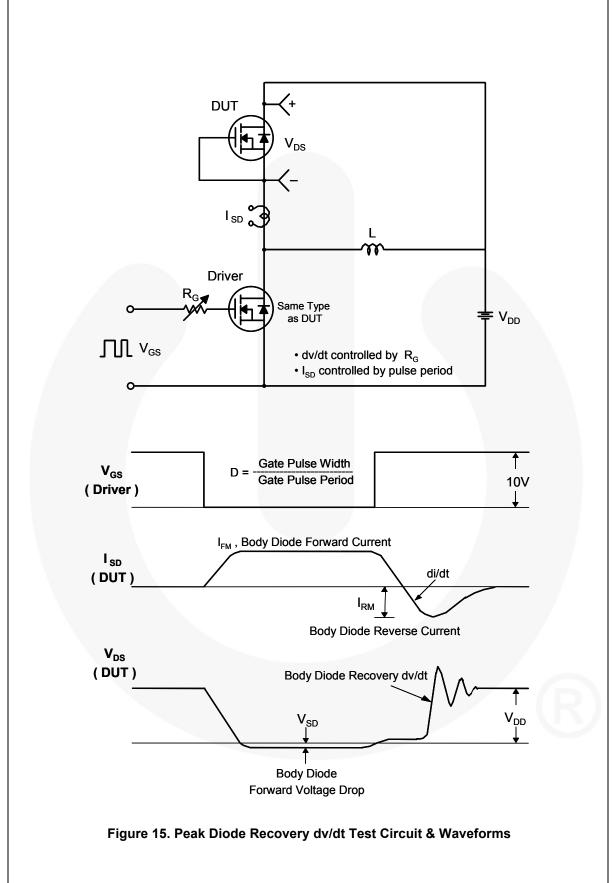


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



# **Mechanical Dimensions**

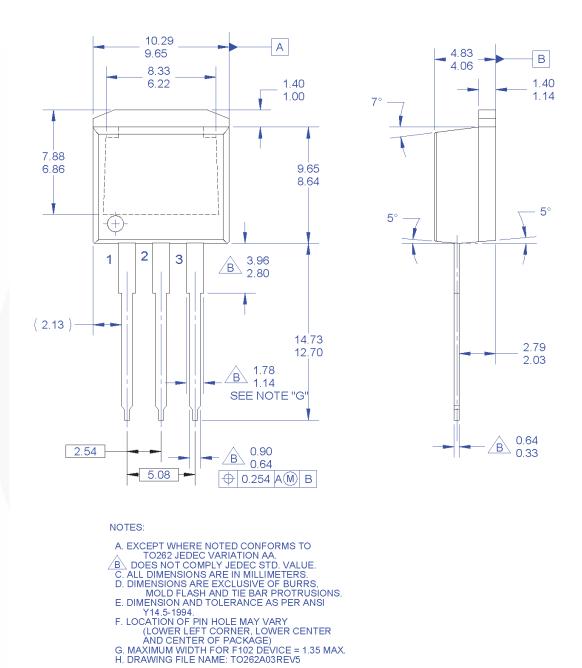


Figure 16. TO262 (I<sup>2</sup>PAK), Molded, 3-Lead, Jedec Variation AA

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